

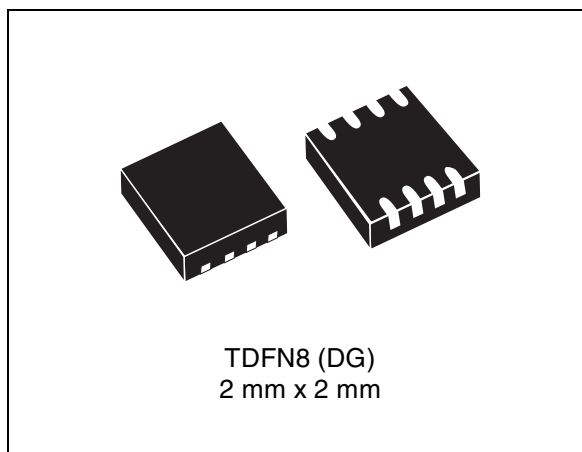


## STM6513

### Dual push-button Smart Reset™ with dual reset outputs and user-selectable setup delay

#### Features

- Dual Smart Reset push-button inputs with user-selectable extended reset setup delay (by three-state input logic):  $t_{SRC} = 2, 6, 10$  s (min.)
- Capacitor-adjustable reset pulse duration ( $t_{REC1}$ )
- Power-on reset
- Dual reset output (RST1 is active-high, push-pull type,  $\overline{RST2}$  is active-low, open-drain)
- Factory-programmable thresholds to monitor  $V_{CC}$  in the range of 1.575 to 4.625 V typ.
- Operating voltage 1.0 V (active-low output valid) to 5.5 V
- Low supply current 3  $\mu$ A
- Operating temperature: industrial grade  $-40$  °C to  $+85$  °C
- TDFN8 package: 2 mm x 2 mm x 0.75 mm
- RoHS compliant



#### Applications

- Mobile phones, smartphones
- e-books
- MP3 players
- Games
- Portable navigation devices
- Any application that requires delayed reset push-button(s) response for improved system stability.

# Contents

<b>1</b>	<b>Description</b> .....	<b>5</b>
<b>2</b>	<b>Device overview</b> .....	<b>7</b>
<b>3</b>	<b>Pin descriptions</b> .....	<b>8</b>
3.1	Power supply ( $V_{CC}$ ) .....	8
3.2	Ground ( $V_{SS}$ ) .....	8
3.3	Smart Reset inputs ( $\overline{SR0}$ , $\overline{SR1}$ ) .....	8
3.4	User-programmable Smart Reset delay (TSR pin) .....	8
3.5	Reset outputs (RST1, $\overline{RST2}$ ) .....	8
3.6	Adjustable output reset timeout period input pin ( $TREC_{ADJ}$ ) .....	8
<b>4</b>	<b>Block diagram</b> .....	<b>10</b>
<b>5</b>	<b>Typical operating characteristics</b> .....	<b>12</b>
<b>6</b>	<b>Maximum rating</b> .....	<b>16</b>
<b>7</b>	<b>DC and AC parameters</b> .....	<b>17</b>
<b>8</b>	<b>Package mechanical data</b> .....	<b>20</b>
<b>9</b>	<b>Package footprint</b> .....	<b>22</b>
<b>10</b>	<b>Tape and reel information</b> .....	<b>23</b>
<b>11</b>	<b>Part numbering</b> .....	<b>26</b>
<b>12</b>	<b>Package marking information</b> .....	<b>27</b>
<b>13</b>	<b>Revision history</b> .....	<b>28</b>

## List of tables

Table 1.	Signal names	7
Table 2.	$t_{REC1}$ programmed by an ideal external capacitor	9
Table 3.	Absolute maximum ratings	16
Table 4.	Operating and measurement conditions	17
Table 5.	DC and AC characteristics	18
Table 6.	Possible $V_{CC}$ voltage thresholds	19
Table 7.	TDFN – 8-lead 2 x 2 x 0.75 mm, 0.5 mm package mechanical data	21
Table 8.	Parameter for landing pattern - TDFN – 8-lead 2 x 2 mm package	22
Table 9.	Carrier tape dimensions	23
Table 10.	Reel dimensions	24
Table 11.	Ordering information scheme	26
Table 12.	Package marking	27
Table 13.	Document revision history	28

## List of figures

Figure 1.	Logic diagram . . . . .	6
Figure 2.	Pin connections . . . . .	6
Figure 3.	Block diagram . . . . .	10
Figure 4.	Typical application diagram . . . . .	11
Figure 5.	Timing waveforms . . . . .	11
Figure 6.	Smart Reset delay $t_{SRC}$ vs. temperature and supply voltage $V_{CC}$ , TSR = $V_{SS}$ . . . . .	12
Figure 7.	Output reset timeout period $t_{REC2}$ vs. temperature and supply voltage $V_{CC}$ ( $t_{REC}$ option E) . . . . .	13
Figure 8.	Supply current $I_{CC}$ vs. temperature and supply voltage $V_{CC}$ . . . . .	13
Figure 9.	Reset voltage $V_{RST}$ (falling) vs. temperature (threshold option S, 2.925 V typ.) . . . . .	14
Figure 10.	Input leakage current, TSR pin, logic low vs. temperature and supply voltage $V_{CC}$ . . . . .	14
Figure 11.	Input leakage current, TSR pin, logic high vs. temperature and supply voltage $V_{CC}$ . . . . .	15
Figure 12.	AC testing input/output waveforms . . . . .	17
Figure 13.	TDFN - 8-lead, 2 x 2 x 0.75 mm, 0.5 mm pitch . . . . .	20
Figure 14.	Landing pattern - TDFN – 8-lead 2 x 2 mm without thermal pad . . . . .	22
Figure 15.	Carrier tape . . . . .	23
Figure 16.	Reel dimensions . . . . .	24
Figure 17.	Tape trailer/leader . . . . .	25
Figure 18.	Pin 1 orientation . . . . .	25
Figure 19.	Package marking area, top view . . . . .	27

# 1 Description

The STM6513 has two separate delayed Smart Reset inputs ( $\overline{\text{SR0}}$ ,  $\overline{\text{SR1}}$ ) which when taken low simultaneously provide three user-selectable delayed Smart Reset setup time ( $t_{\text{SRC}}$ ) options of 2 s, 6 s and 10 s. These are selected through a three-state TSR input pin: when connected to ground,  $t_{\text{SRC}} = 2$  s; when left open,  $t_{\text{SRC}} = 6$  s; when connected to  $V_{\text{CC}}$ ,  $t_{\text{SRC}} = 10$  s (all the times are minimum). There are two reset outputs, both going active simultaneously after both the Smart Reset inputs were held active for the selected  $t_{\text{SRC}}$  delay time. The first reset output, RST1, is active-high, push-pull; the second reset output,  $\overline{\text{RST2}}$ , is active-low, open-drain requiring an external pull-up resistor. The duration of the output reset pulses is independently programmable:  $t_{\text{REC1}}$  is user-programmable (by external capacitor  $C_{\text{iREC}}$ ),  $t_{\text{REC2}}$  is factory-programmed to 210 ms (typ.), with the option of 360 ms typ. Additionally, the  $V_{\text{CC}}$  is monitored and if it drops below the selected  $V_{\text{RST}}$  threshold, both the reset outputs go active and remain so while  $V_{\text{CC}}$  is below the  $V_{\text{RST}}$  threshold, plus the defined duration of the reset pulse  $t_{\text{REC}}$  on each output.

## Smart Reset devices

The Smart Reset device family STM65xx provides a useful feature that ensures inadvertent short reset push-button closures do not cause system resets. This is done by implementing extended Smart Reset input delay ( $t_{\text{SRC}}$ ). Once the valid Smart Reset input levels and setup delay are met, the device generates an output reset pulse with user-programmable timeout period ( $t_{\text{REC}}$ ).

The Smart Reset inputs can be also connected to the applications interrupt to allow the control of both the interrupt pin and the hard reset functions. If the push-buttons are closed for a short time, the processor is only interrupted. If the system still does not respond properly, holding the push-buttons for the extended setup time ( $t_{\text{SRC}}$ ) causes hard reset of the processor through the reset outputs. The Smart Reset feature helps significantly increase system stability.

The STM65xx family of Smart Reset devices consists of low current microprocessor reset circuits targeted at applications such as MP3 players, navigation, smartphones or mobile phones; generally any application that requires delayed reset push-button(s) response for improved system stability. The STM65xx devices feature single or dual Smart Reset inputs (SR). The delayed Smart Reset setup time ( $t_{\text{SRC}}$ ) options of 2 s, 6 s and 10 s (all min.) are adjustable by an external capacitor on the SRC pin or selectable by three-state logic. The delayed setup period ignores switch closures shorter than  $t_{\text{SRC}}$ , thus preventing unwanted resets.

The STM65xx devices have active-low (optionally active-high) open-drain reset ( $\overline{\text{RST}}$ ) output(s) with or without internal pull-up resistor or push-pull as output options, with factory-programmed or capacitor-adjustable or push-buttons defined output reset pulse duration, with or without power-on reset function.

Some devices also have an undervoltage monitoring feature: the reset output is also asserted when the monitored supply voltage  $V_{\text{CC}}$  drops below the specified threshold. The reset output remains asserted for the reset timeout period ( $t_{\text{REC}}$ ) after the monitored supply voltage goes above the specified threshold.

Figure 1. Logic diagram

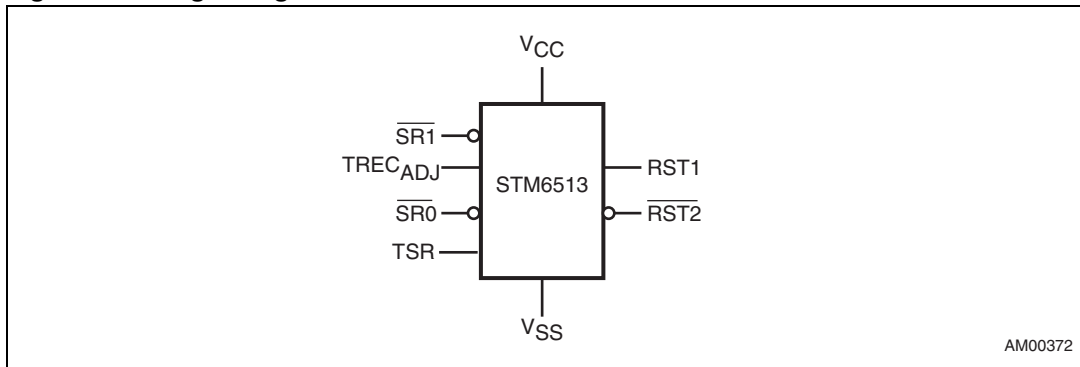
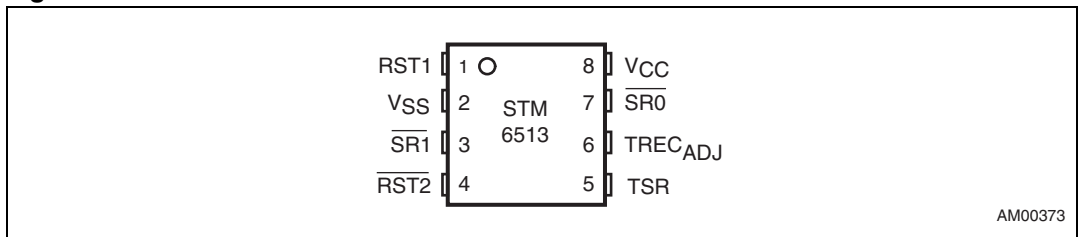


Figure 2. Pin connections



## 2 Device overview

**Table 1. Signal names**

Symbol	Input/output	Description
RST1	Output	First reset output, active-high, push-pull.
$\overline{\text{RST2}}$	Output	Second reset output, active-low, open-drain.
$\overline{\text{SR0}}$	Input	Primary push-button Smart Reset input. Active-low.
$\overline{\text{SR1}}$	Input	Secondary push-button Smart Reset input. Active-low.
TSR	Input	A Three-state Smart Reset input delay setup control. When connected to ground, $t_{\text{SRC}} = 2$ s; when left open, $t_{\text{SRC}} = 6$ s; when connected to $V_{\text{CC}}$ , $t_{\text{SRC}} = 10$ s (all times are minimum). TSR is a DC-type input, intended to be either permanently grounded, permanently connected to $V_{\text{CC}}$ or permanently left open. If left open, for improved system glitch immunity it is strongly recommended to connect a 0.1 $\mu\text{F}$ decoupling ceramic capacitor between the TSR and $V_{\text{SS}}$ pins.
TREC <sub>ADJ</sub>	Input	Input pin for $t_{\text{REC1}}$ reset pulse duration adjustment. Connect an external capacitor $C_{\text{tREC}}$ to this pin to determine $t_{\text{REC1}}$ ; $t_{\text{REC2}}$ is factory-programmed.
$V_{\text{CC}}$	Supply	Positive supply voltage input. Power supply for the device and an input for the monitored supply voltage. A 0.1 $\mu\text{F}$ decoupling ceramic capacitor is recommended to be connected between $V_{\text{CC}}$ and $V_{\text{SS}}$ pins.
$V_{\text{SS}}$	Supply	Ground

## 3 Pin descriptions

### 3.1 Power supply ( $V_{CC}$ )

This pin is used to provide the power to the Smart Reset device and to monitor the power supply. A 0.1  $\mu\text{F}$  decoupling ceramic capacitor is recommended to be connected between  $V_{CC}$  and  $V_{SS}$  pins.

### 3.2 Ground ( $V_{SS}$ )

This is the ground for the device and all supplies.

### 3.3 Smart Reset inputs ( $\overline{\text{SR0}}$ , $\overline{\text{SR1}}$ )

Push-button Smart Reset inputs. Both inputs need to be held active at the same time for at least  $t_{\text{SRC}}$  to activate the reset outputs. When only one Smart Reset input is used, connect the unused one permanently to  $V_{SS}$ .

### 3.4 User-programmable Smart Reset delay (TSR pin)

Used to allow the user to program the setup time before the push-buttons action is validated by reset output. Controlled by different voltage levels on the TSR pin: when connected to ground,  $t_{\text{SRC}} = 2$  s; when left open,  $t_{\text{SRC}} = 6$  s; when connected to  $V_{CC}$ ,  $t_{\text{SRC}} = 10$  s (all times are minimum). TSR is a DC-type input, intended to be either permanently grounded, permanently connected to  $V_{CC}$  or permanently left open. If left open, for improved system glitch immunity it is strongly recommended to connect a 0.1  $\mu\text{F}$  decoupling ceramic capacitor between the TSR and  $V_{SS}$  pins.

### 3.5 Reset outputs ( $\text{RST1}$ , $\overline{\text{RST2}}$ )

Reset outputs, RST1 active-high, push-pull type,  $\overline{\text{RST2}}$  active-low, open-drain.

### 3.6 Adjustable output reset timeout period input pin ( $\text{TREC}_{\text{ADJ}}$ )

The output reset timeout period ( $t_{\text{REC1}}$ ) on RST1 is adjustable by connecting an external capacitor  $C_{\text{TREC}}$  to the  $\text{TREC}_{\text{ADJ}}$  pin. Calculated  $t_{\text{REC}}$  and  $C_{\text{TREC}}$  examples are given in [Table 2](#). Refer also to [Table 5](#).



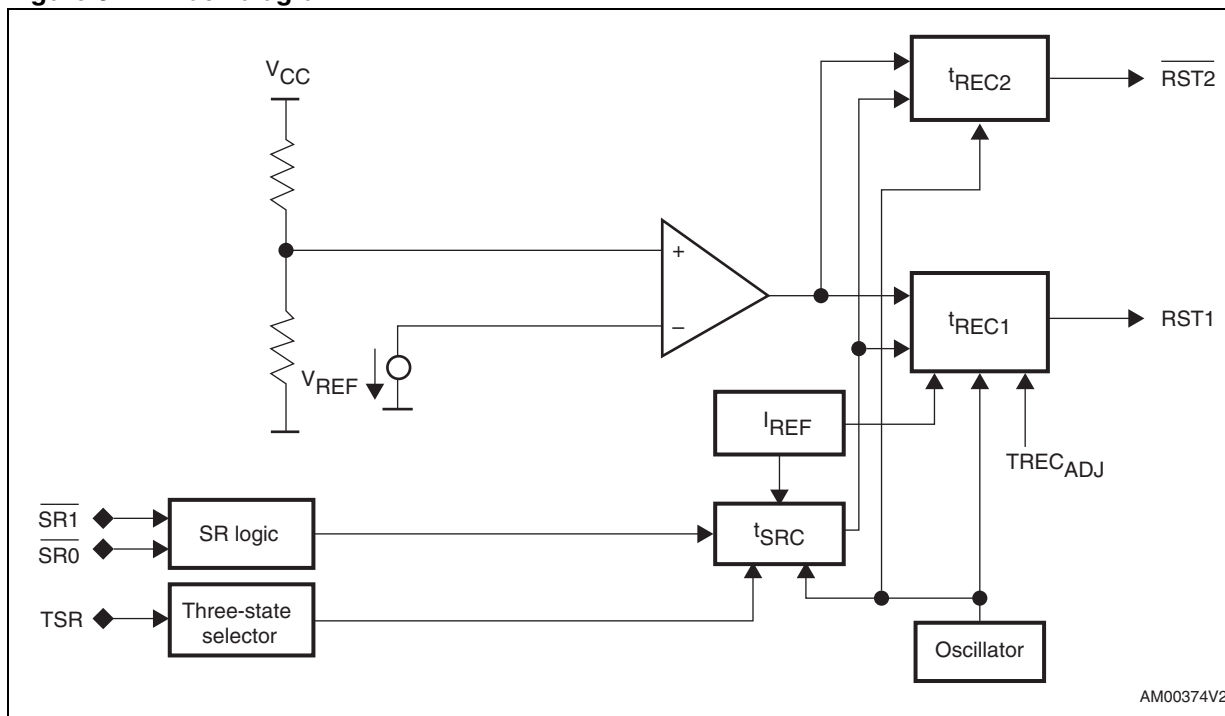
**Table 2.  $t_{REC1}$  programmed by an ideal external capacitor**

$C_{iREC}$ value ( $\mu\text{F}$ )	$t_{REC1}$ (ms) <sup>(1)(2)</sup>			Closest common $C_{iREC}$ value ( $\mu\text{F}$ )
	Min.	Typ.	Max.	
0.001	10	15	20	0.001
0.002	20	30	40	0.0022
0.01	100	150	200	0.01
0.014	140	210	280	0.015
0.028	280	420	560	0.027
0.056	560	840	1120	0.056
0.112	1120	1680	2240	0.12

1. At 25 ° C. Example calculations based on an ideal capacitor. During application design and component selection it should be considered that the current flowing into the external  $t_{REC}$  programming capacitor ( $C_{iREC}$ ) is on the order of 100 nA, therefore a low-leakage capacitor (ceramic or film capacitor) should be used and placed as close as possible to the  $TREC_{ADJ}$  pin. Also an adequate low-leakage PCB environment should be ensured to prevent  $t_{REC}$  accuracy from being affected. A recommended minimum value of  $C_{iREC}$  is 0.001  $\mu\text{F}$ .
2. In case of repeated activations of the internal  $t_{REC}$  timer, an interval of 10 ms min. is needed between  $t_{REC}$  intervals to fully discharge  $C_{iREC}$ , so that the next  $t_{REC1}$  is as specified.

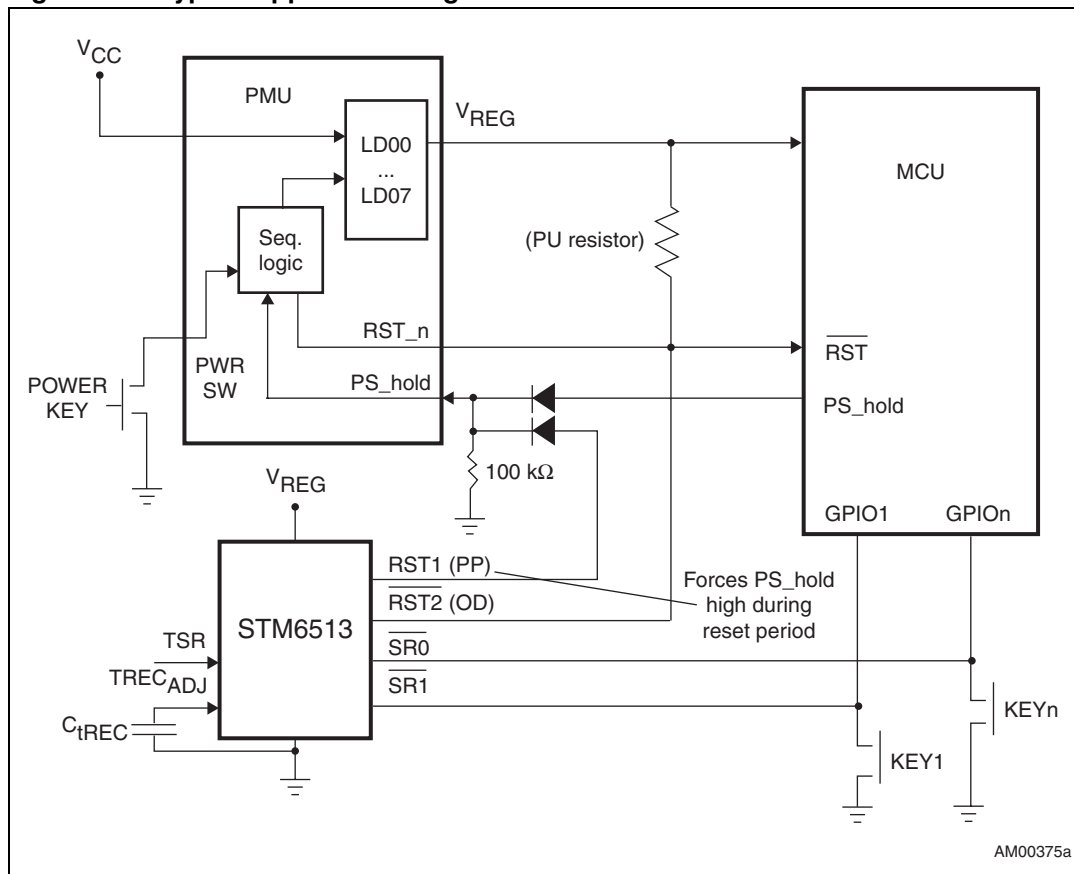
# 4 Block diagram

Figure 3. Block diagram



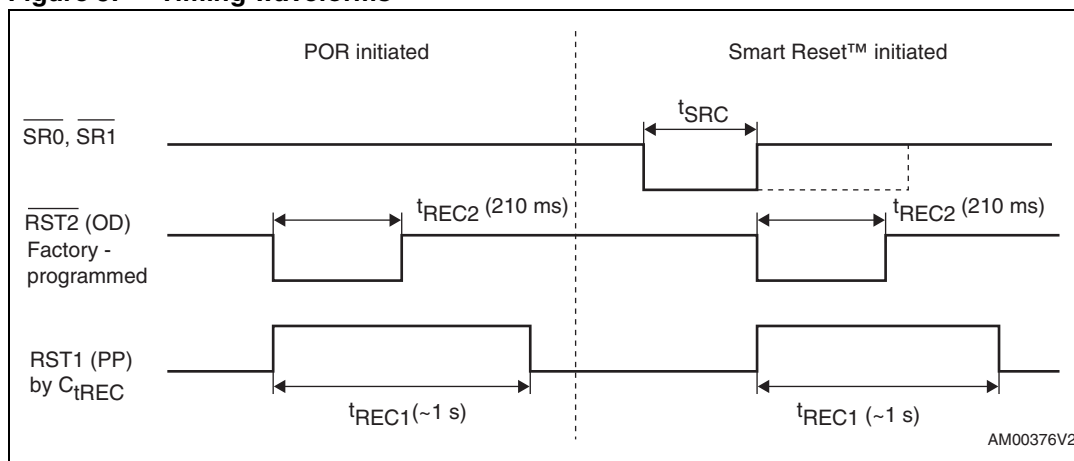
STM6513 hookup with RST1 and  $\overline{\text{RST2}}$ , bridging the PS\_hold reset pulse during the microprocessor reset initiated by the STM6513 Smart Reset device:

Figure 4. Typical application diagram



AM00375a

Figure 5. Timing waveforms



AM00376V2

## 5 Typical operating characteristics

Figure 6. Smart Reset delay  $t_{SRC}$  vs. temperature and supply voltage  $V_{CC}$ ,  $TSR = V_{SS}$

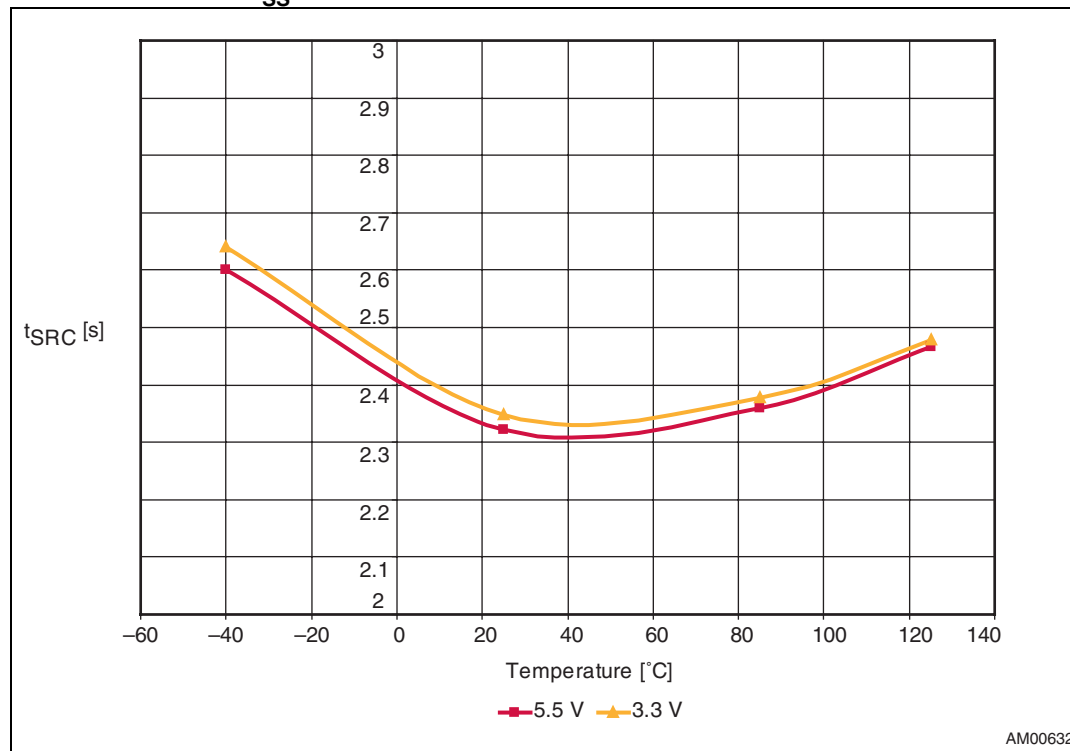


Figure 7. Output reset timeout period  $t_{REC2}$  vs. temperature and supply voltage  $V_{CC}$  ( $t_{REC}$  option E)

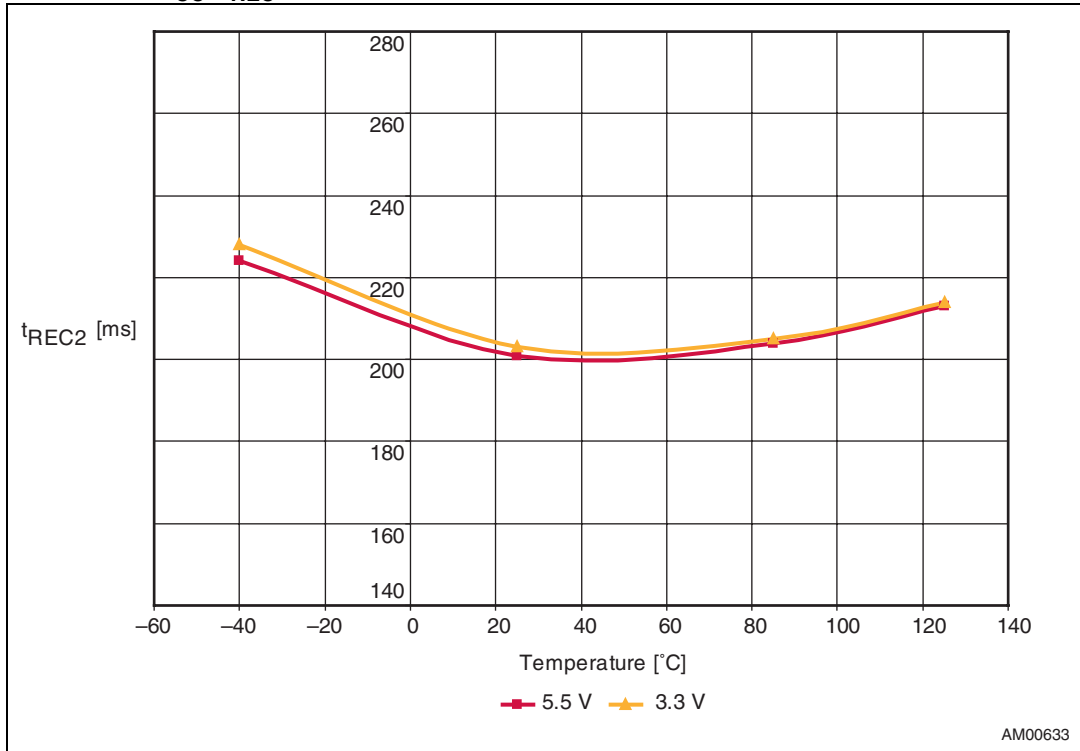


Figure 8. Supply current  $I_{CC}$  vs. temperature and supply voltage  $V_{CC}$

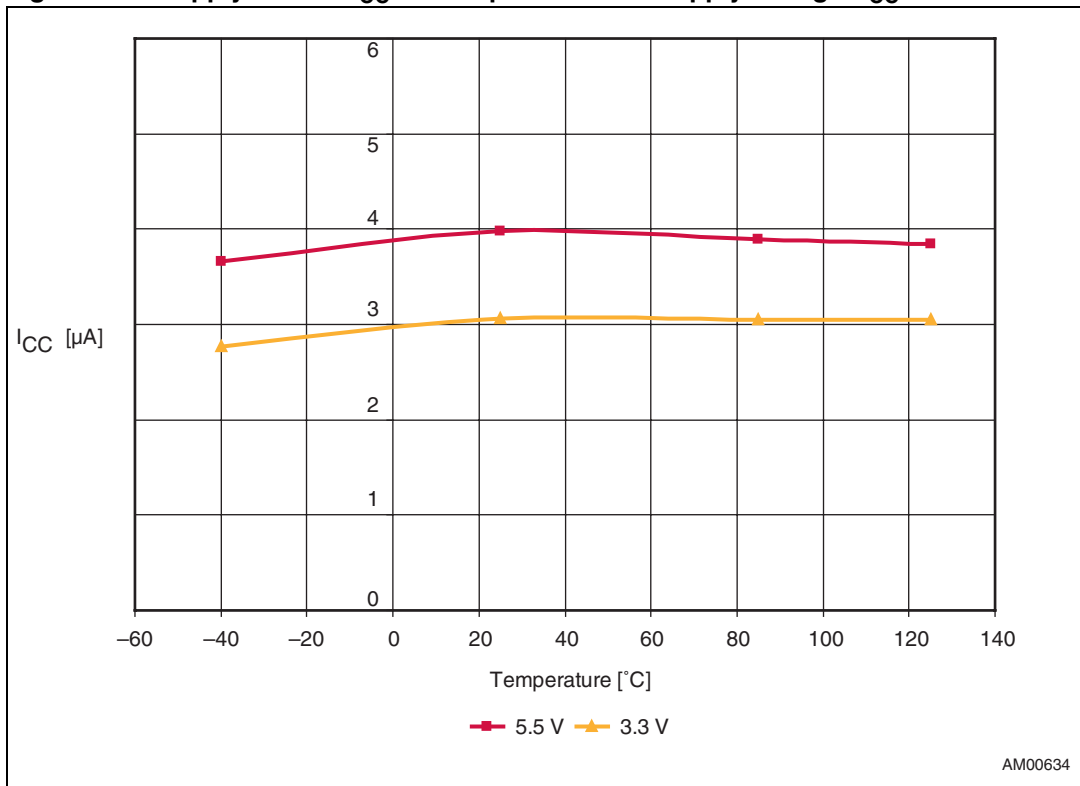


Figure 9. Reset voltage  $V_{RST}$  (falling) vs. temperature (threshold option S, 2.925 V typ.)

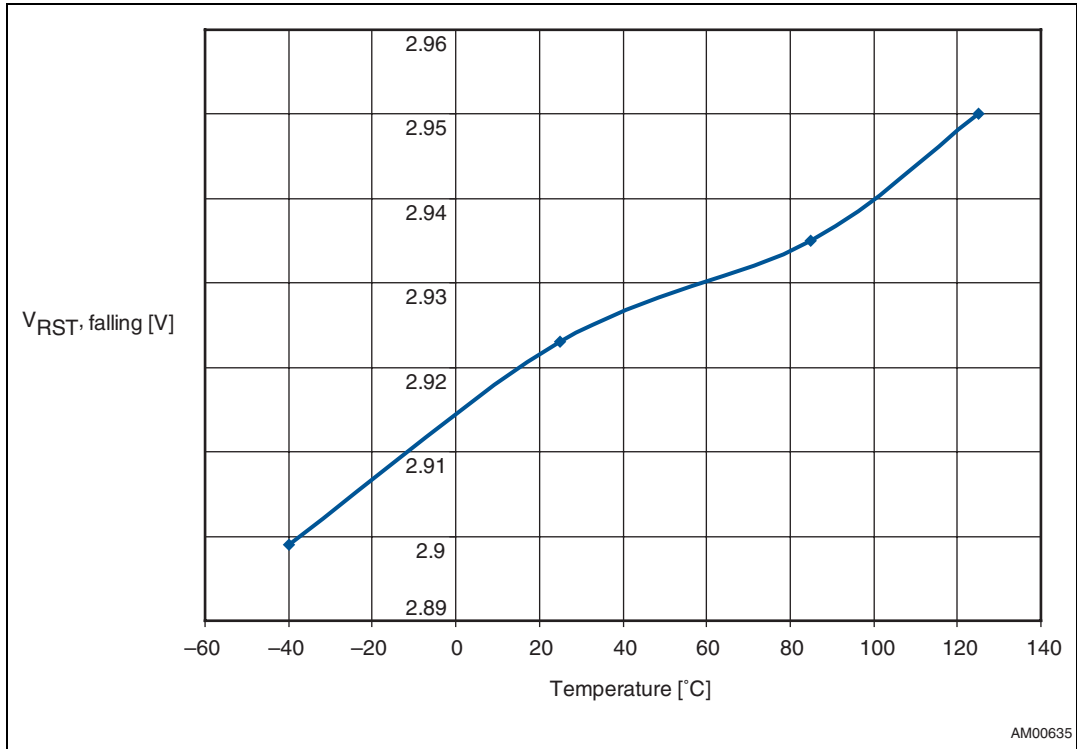


Figure 10. Input leakage current, TSR pin, logic low vs. temperature and supply voltage  $V_{CC}$

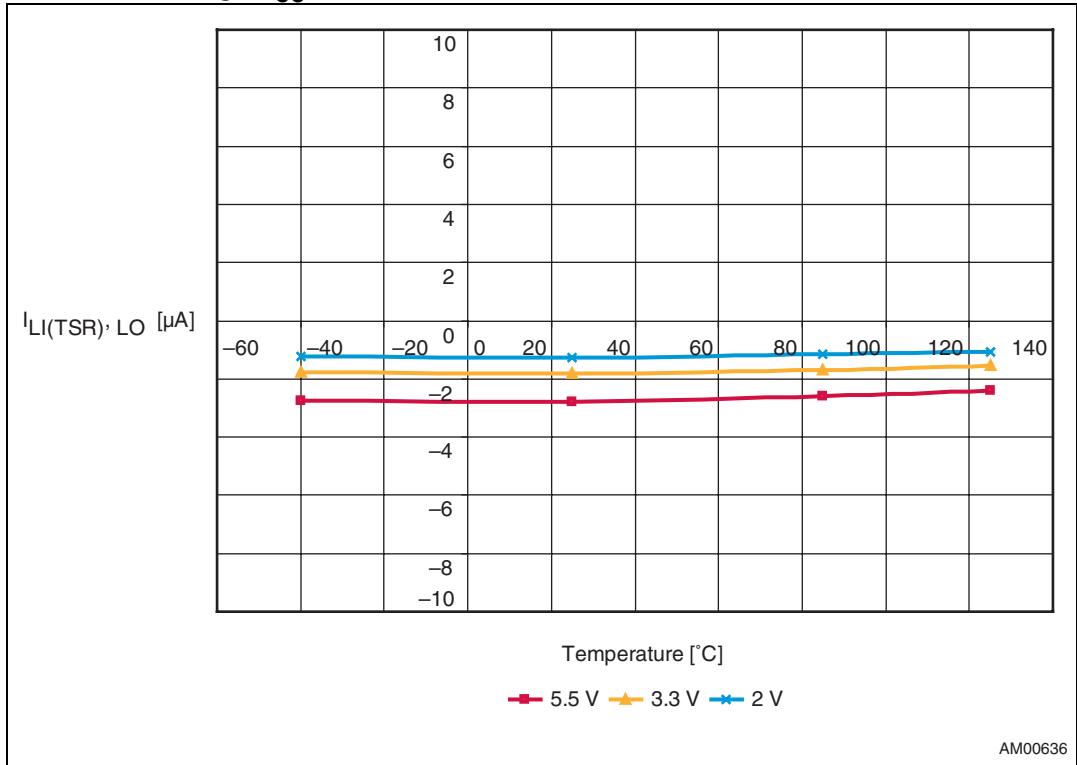
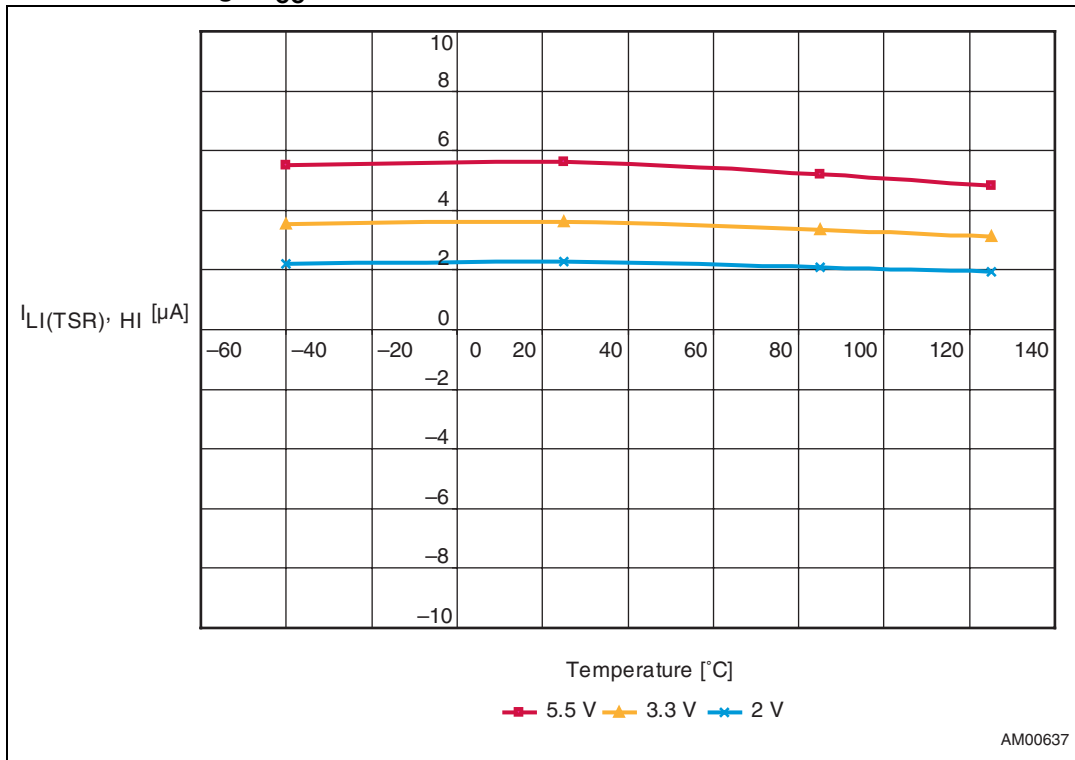


Figure 11. Input leakage current, TSR pin, logic high vs. temperature and supply voltage V<sub>CC</sub>



## 6 Maximum rating

Stressing the device above the rating listed in the [Table 3: Absolute maximum ratings](#) may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

**Table 3. Absolute maximum ratings**

Symbol	Parameter		Value	Unit
$T_{STG}$	Storage temperature ( $V_{CC}$ off)		-55 to +150	°C
$T_{SLD}^{(1)}$	Lead solder temperature for 10 seconds		260	°C
$\theta_{JA}$	Thermal resistance (junction to ambient)	TDFN8	149.0	°C/W
$V_{IO}$	Input or output voltage		-0.3 to 5.5 <sup>(2)</sup>	V
$V_{CC}$	Supply voltage		-0.3 to 7	V

1. Reflow at peak temperature of 260 °C. The time above 255 °C must not exceed 30 s.
2. For RST1 -0.3 to  $V_{CC}$  +0.3 V only.



## 7 DC and AC parameters

This section summarizes the operating measurement conditions, and the DC and AC characteristics of the device. The parameters in the [Table 5: DC and AC characteristics](#) that follow, are derived from tests performed under the Measurement Conditions summarized in [Table 4.: Operating and measurement conditions](#). Designers should check that the operating conditions in their circuit match the operating conditions when relying on the quoted parameters.

**Table 4. Operating and measurement conditions**

Parameter	Value	Unit
V <sub>CC</sub> supply voltage	1.0 to 5.5	V
Ambient operating temperature (T <sub>A</sub> )	-40 to +85	°C
Input rise and fall times	≤ 5	ns
Input pulse voltages	0.2 to 0.8 V <sub>CC</sub>	V
Input and output timing ref. voltages	0.3 to 0.7 V <sub>CC</sub>	V

**Figure 12. AC testing input/output waveforms**

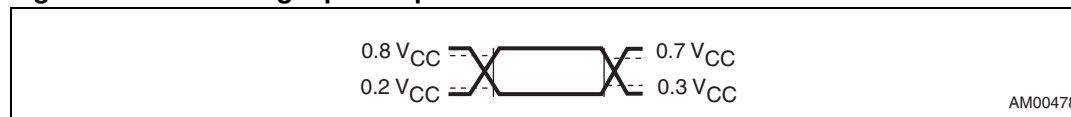


Table 5. DC and AC characteristics

Symbol	Parameter	Test conditions <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Units
V <sub>CC</sub>	Supply voltage range	Reset output valid - active-low	1.0		5.5	V
		Reset output valid - active-high	1.2		5.5	V
I <sub>CC</sub>	Supply current (V <sub>CC</sub> )	V <sub>CC</sub> = 3.0 V, TSR left open <sup>(3)</sup>		3	5	μA
		V <sub>CC</sub> = 5.0 V, TSR left open		4	6	μA
V <sub>OL</sub>	Reset output voltage low	V <sub>CC</sub> ≥ 4.5 V, sinking 3.2 mA			0.3	V
		V <sub>CC</sub> ≥ 3.3 V, sinking 2.5 mA			0.3	V
		V <sub>CC</sub> ≥ 1.0 V, sinking 0.1 mA			0.3	V
V <sub>OH</sub>	Reset output voltage high, RST1	V <sub>CC</sub> ≥ 4.5 V, I <sub>SOURCE</sub> = 0.8 mA	0.8 V <sub>CC</sub>			V
		V <sub>CC</sub> ≥ 2.7 V, I <sub>SOURCE</sub> = 0.5 mA	0.8 V <sub>CC</sub>			V
		V <sub>CC</sub> ≥ 1.2 V, I <sub>SOURCE</sub> = 0.05 mA	0.8 V <sub>CC</sub>			V
V <sub>RST</sub>	Fixed voltage trip point for V <sub>CC</sub> monitoring (refer to <a href="#">Table 6</a> )	-40 to +85 °C	V <sub>RST</sub> -2.5%	V <sub>RST</sub>	V <sub>RST</sub> +2.5%	V
		25 °C	V <sub>RST</sub> -2.0%	V <sub>RST</sub>	V <sub>RST</sub> +2.0%	V
V <sub>HYST</sub>	Hysteresis of V <sub>RST</sub>	L, M		0.5%		
		T, S, R, Z, Y, W, V		1%		
	V <sub>CC</sub> to reset delay <sup>(4)</sup>	V <sub>CC</sub> falling from (V <sub>RST</sub> + 100 mV) to (V <sub>RST</sub> - 100 mV) at 10 mV/μs		20		μs
t <sub>REC2</sub>	Output reset timeout period on $\overline{\text{RST2}}$ , factory-programmed	Option E	140	210	280	ms
		Option F	240	360	480	ms
t <sub>REC1</sub>	User-adjustable output reset timeout period on RST1 Refer to <a href="#">Table 2</a> .		10 000 x C <sub>tREC</sub> (μF)	15 000 x C <sub>tREC</sub> (μF)	20 000 x C <sub>tREC</sub> (μF)	ms

Table 5. DC and AC characteristics (continued)

Symbol	Parameter	Test conditions <sup>(1)</sup>	Min.	Typ. <sup>(2)</sup>	Max.	Units
<b>Smart Reset inputs (<math>\overline{\text{SRx}}</math>)</b>						
$t_{\text{SRC}}$	Smart Reset delay	TSR = $V_{\text{SS}}$	2	2.5	3	s
		TSR = floating	6	7.5	9	s
		TSR = $V_{\text{CC}}$	10	12.5	15	s
$V_{\text{IL}}$	$\overline{\text{SR0}}$ , $\overline{\text{SR1}}$ input voltage low		$V_{\text{SS}} - 0.3$		$0.3 V_{\text{CC}}$	V
$V_{\text{IH}}$	$\overline{\text{SR0}}$ , $\overline{\text{SR1}}$ input voltage high		$0.7 V_{\text{CC}}$		5.5	V
	Input glitch immunity <sup>(5)</sup>	Corresponds to the actual $t_{\text{SRC}}$		$t_{\text{SRC}}$		s
$I_{\text{LI(SR)}}$	Input leakage current ( $\overline{\text{SR0}}$ , $\overline{\text{SR1}}$ pins)		-1		1	$\mu\text{A}$
$I_{\text{LI(TSR)}}$	Input leakage current (TSR pin)		-5		7	$\mu\text{A}$

- Valid for ambient operating temperature:  $T_{\text{A}} = -40$  to  $+85$  °C;  $V_{\text{CC}} = 1.0$  V to 5.5 V (except where noted).
- Typical value is at 25 °C and  $V_{\text{CC}} = 3.3$  V unless otherwise noted.
- For devices with  $V_{\text{RST}} < 3.0$  V.
- Guaranteed by design.
- Input glitch immunity is equal to  $t_{\text{SRC}}$  (when both SR inputs are low), otherwise infinite.

Table 6. Possible  $V_{\text{CC}}$  voltage thresholds

$V_{\text{CC}}$ monitoring threshold $V_{\text{RST}}$	Typ.	$\pm 2.5\%$ ( $-40$ °C to $+85$ °C)		$\pm 2.0\%$ (25 °C)		Unit
		Min.	Max.	Min.	Max.	
L (falling)	4.625	4.509	4.741	4.533	4.718	V
M (falling)	4.375	4.266	4.484	4.288	4.463	V
T (falling)	3.075	2.998	3.152	3.014	3.137	V
S (falling)	2.925	2.852	2.998	2.867	2.984	V
R (falling)	2.625	2.559	2.691	2.573	2.678	V
Z (falling)	2.313	2.255	2.371	2.267	2.359	V
Y (falling)	2.188	2.133	2.243	2.144	2.232	V
W (falling)	1.665	1.623	1.707	1.632	1.698	V
V (falling)	1.575	1.536	1.614	1.544	1.607	V

## 8 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

**Figure 13. TDFN - 8-lead, 2 x 2 x 0.75 mm, 0.5 mm pitch**

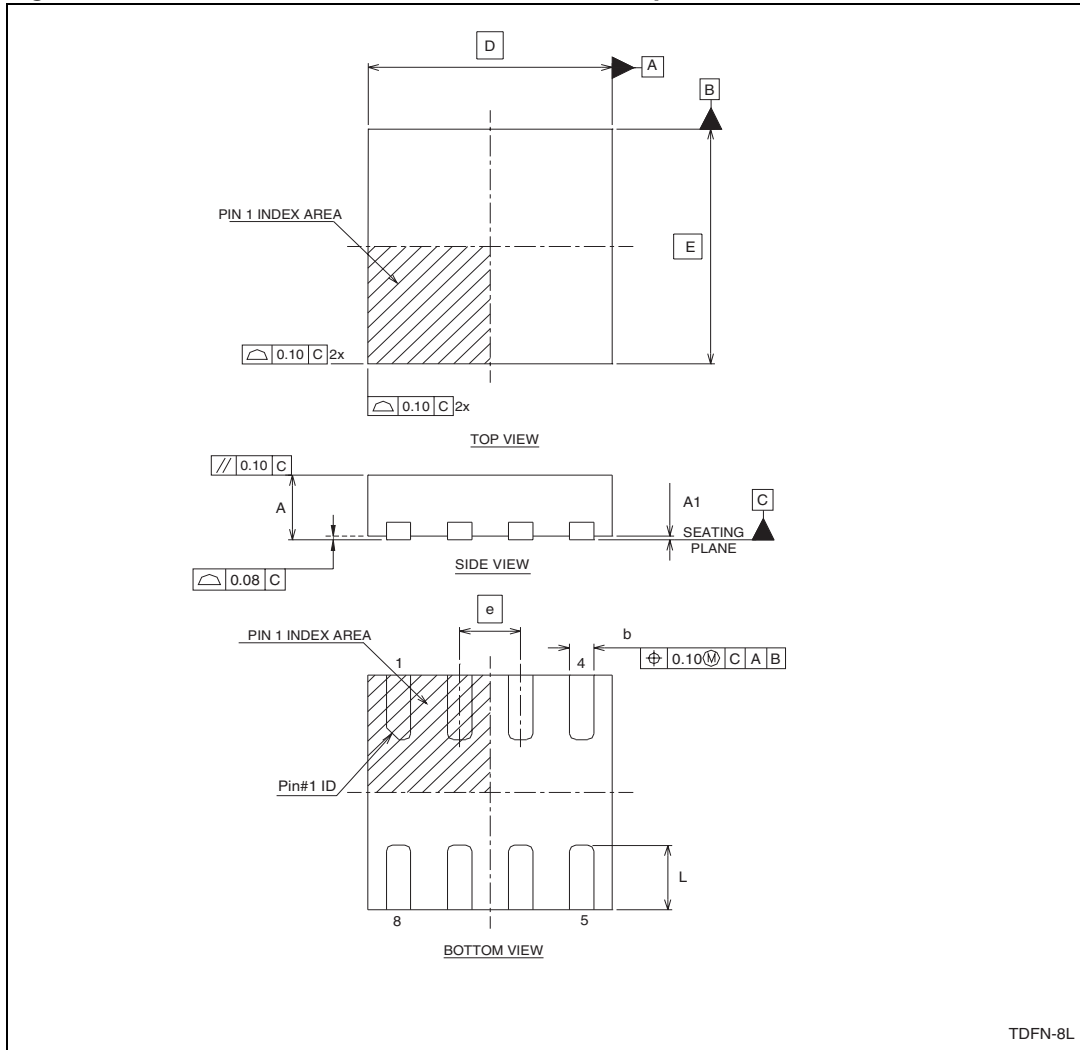


Table 7. TDFN – 8-lead 2 x 2 x 0.75 mm, 0.5 mm package mechanical data

Symbol	Dimension (mm)			Dimension (inches)		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
b	0.15	0.20	0.25	0.006	0.008	0.010
D BSC	1.9	2.00	2.1	0.075	0.079	0.083
E BSC	1.9	2.00	2.1	0.075	0.079	0.083
e		0.50			0.020	
L	0.45	0.55	0.65	0.018	0.022	0.026

## 9 Package footprint

Figure 14. Landing pattern - TDFN – 8-lead 2 x 2 mm without thermal pad

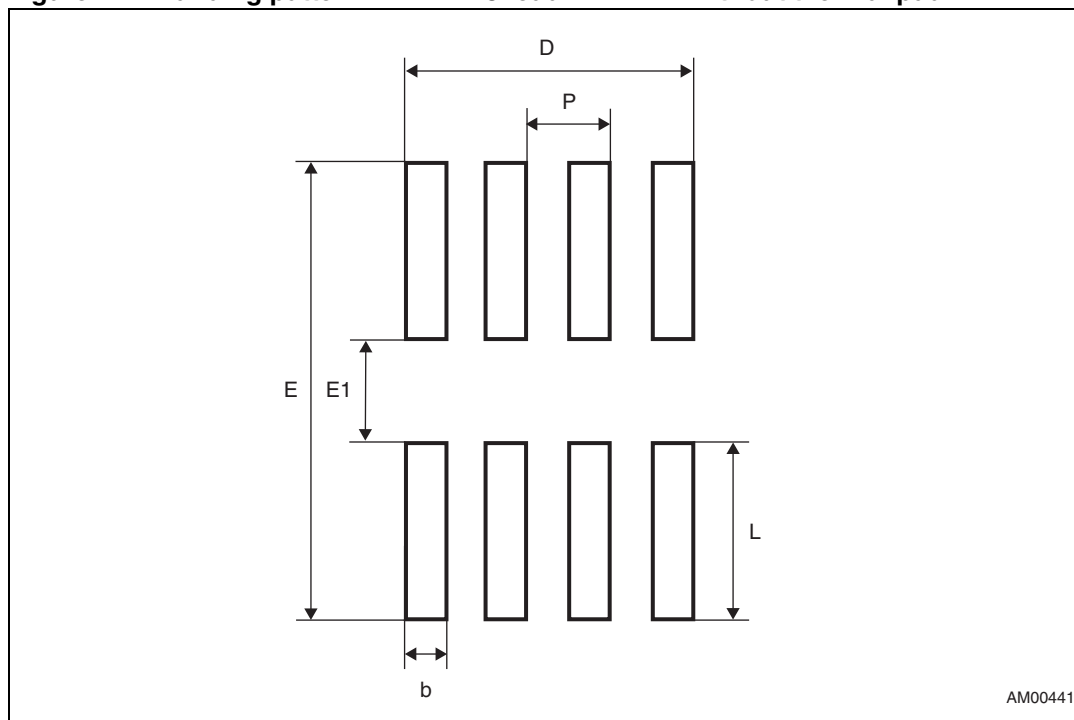


Table 8. Parameter for landing pattern - TDFN – 8-lead 2 x 2 mm package

Parameter	Description	Dimension (mm)		
		Min.	Nom.	Max.
L	Contact length	1.05	—	1.15
b	Contact width	0.25	—	0.30
E	Max. land pattern Y-direction	—	2.85	—
E1	Contact gap spacing	—	0.65	—
D	Max. land pattern X-direction	—	1.75	—
P	Contact pitch	—	0.5	—

# 10 Tape and reel information

Figure 15. Carrier tape

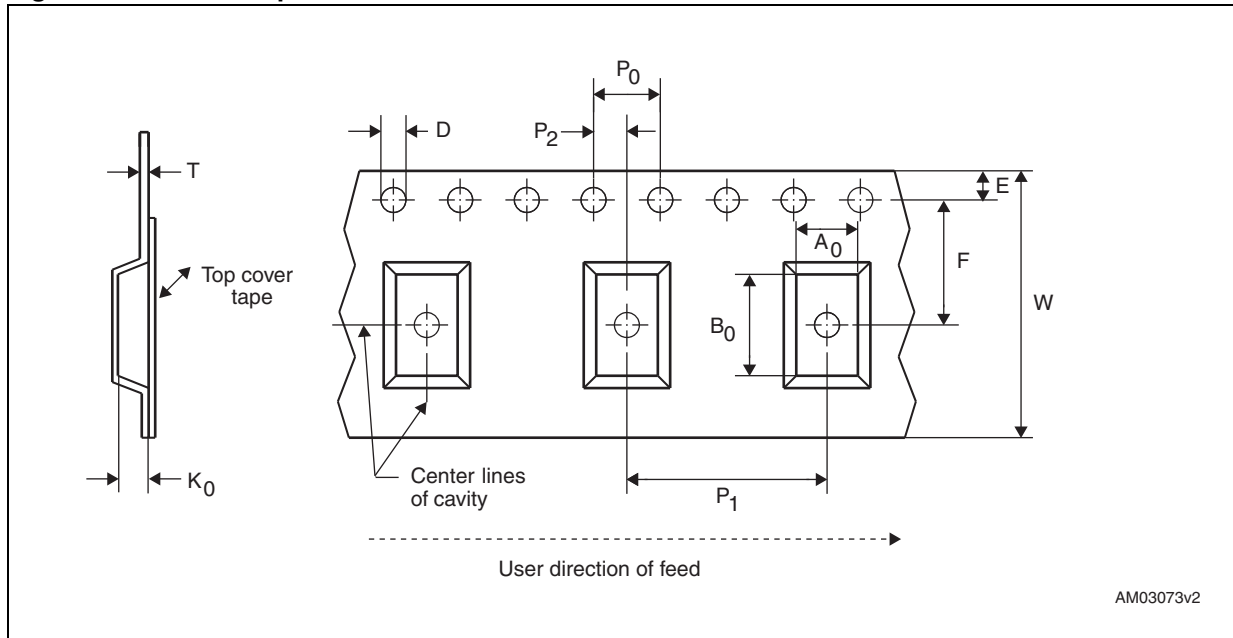


Table 9. Carrier tape dimensions

Package	W	D	E	P <sub>0</sub>	P <sub>2</sub>	F	A <sub>0</sub>	B <sub>0</sub>	K <sub>0</sub>	P <sub>1</sub>	T	Unit	Bulk qty.
TDFN8	8.00 +0.30 -0.10	1.50 +0.10/ -0.00	1.75 ±0.10	4.00 ±0.10	2.00 ±0.10	3.50 ±0.05	2.30 ±0.05	2.30 ±0.05	1.00 ±0.05	4.00 ±0.10	0.250 ±0.05	mm	3000

Figure 16. Reel dimensions

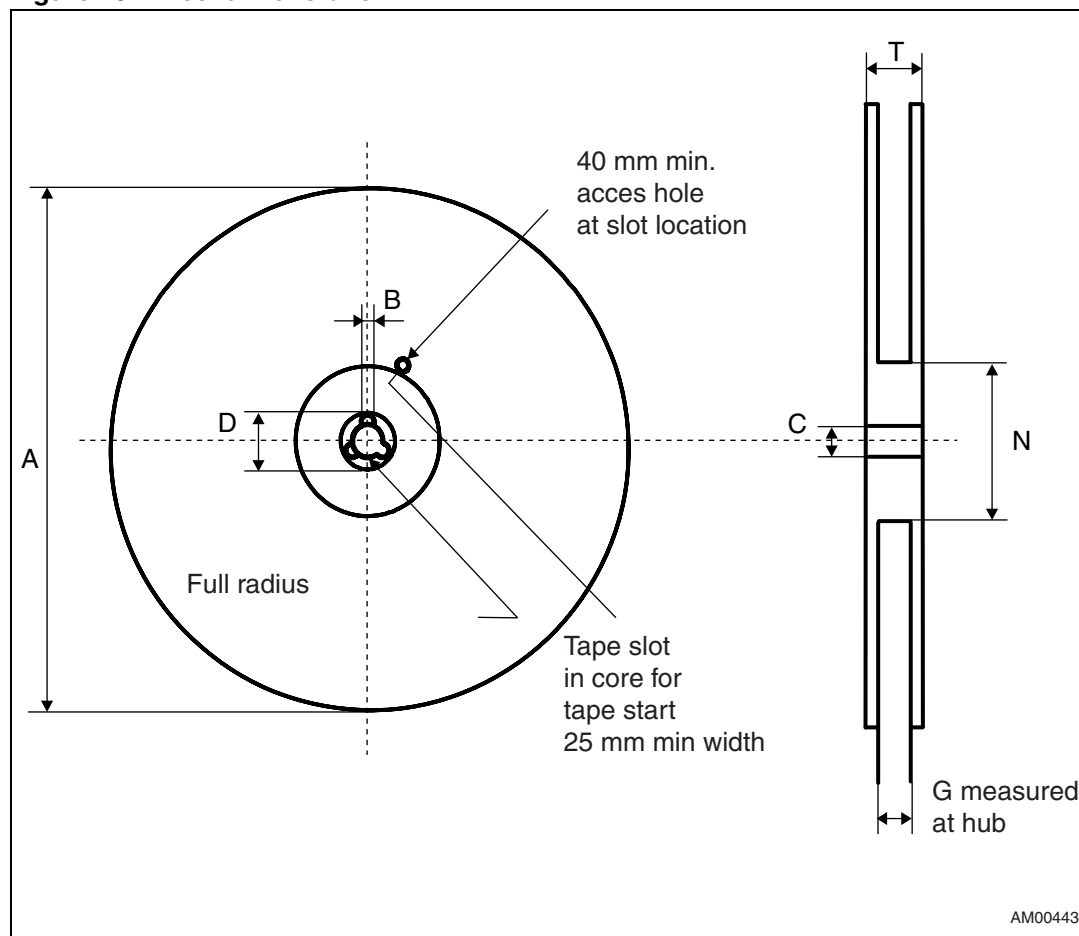


Table 10. Reel dimensions

Tape sizes	A max.	B min.	C	D min.	N min.	G	T max.
8 mm	180 (7 inches)	1.50	13.0 +/- 0.20	20.20	60	8.4 +2/-0	14.40



Figure 17. Tape trailer/leader

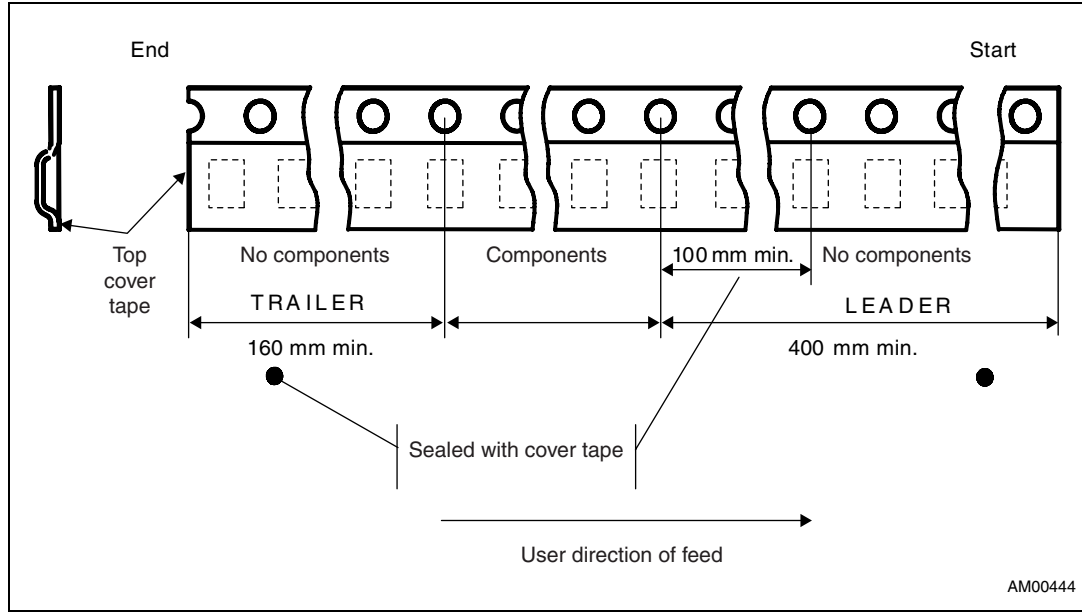
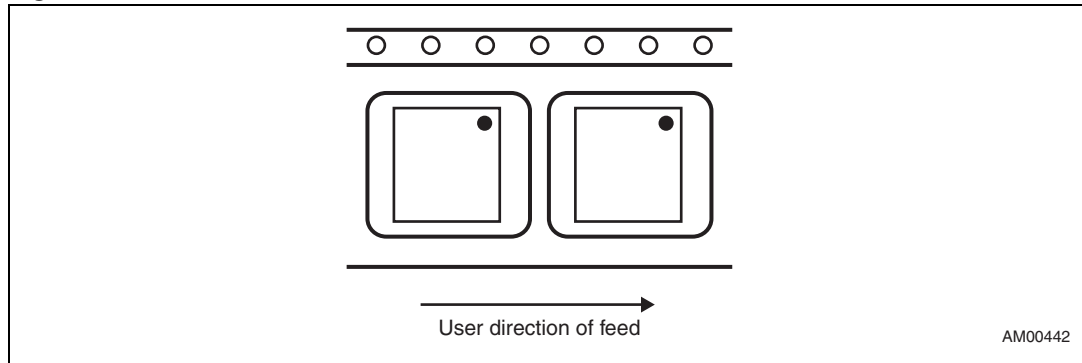


Figure 18. Pin 1 orientation



- Note: 1 Drawings are not to scale.  
 2 All dimensions are in mm, unless otherwise noted.

# 11 Part numbering

**Table 11. Ordering information scheme**

Example:

STM6513 V E I E DG 6 F

**Device type**

STM6513

**Reset ( $V_{CC}$  monitoring threshold) voltage  $V_{RST}$**

L = 4.625 V (typ., falling)

M = 4.375 V

T = 3.075 V

S = 2.925 V

R = 2.625 V

Z = 2.313 V

Y = 2.188 V

W = 1.665 V

V = 1.575 V

**Smart Reset setup delay ( $t_{SRC}$ );  
presence of internal input pull-up on all Smart Reset inputs ( $\overline{SR0}$ ,  $\overline{SR1}$ )**

E = 2 or 6 or 10 s min., user-programmed (three-state); no input pull-up

**Outputs type**

I = RST1 active-high, push-pull,  $\overline{RST2}$  active-low, open-drain, no pull-up

**Reset timeout period ( $t_{REC}$ )**

E =  $t_{REC1}$  user-programmable (external capacitor),  $t_{REC2}$  factory-programmed (210 ms typ.)

F =  $t_{REC1}$  user-programmable (external capacitor),  $t_{REC2}$  factory-programmed (360 ms typ.)

**Package**

DG = TDFN8 - 2 x 2 x 0.75 mm, 0.5 mm pitch

**Temperature range**

6 = -40 °C to +85 °C

**Shipping method**

F = ECOPACK® package, tape and reel

For other options, voltage threshold values etc. or for more information on any aspect of this device, please contact the ST sales office nearest you.

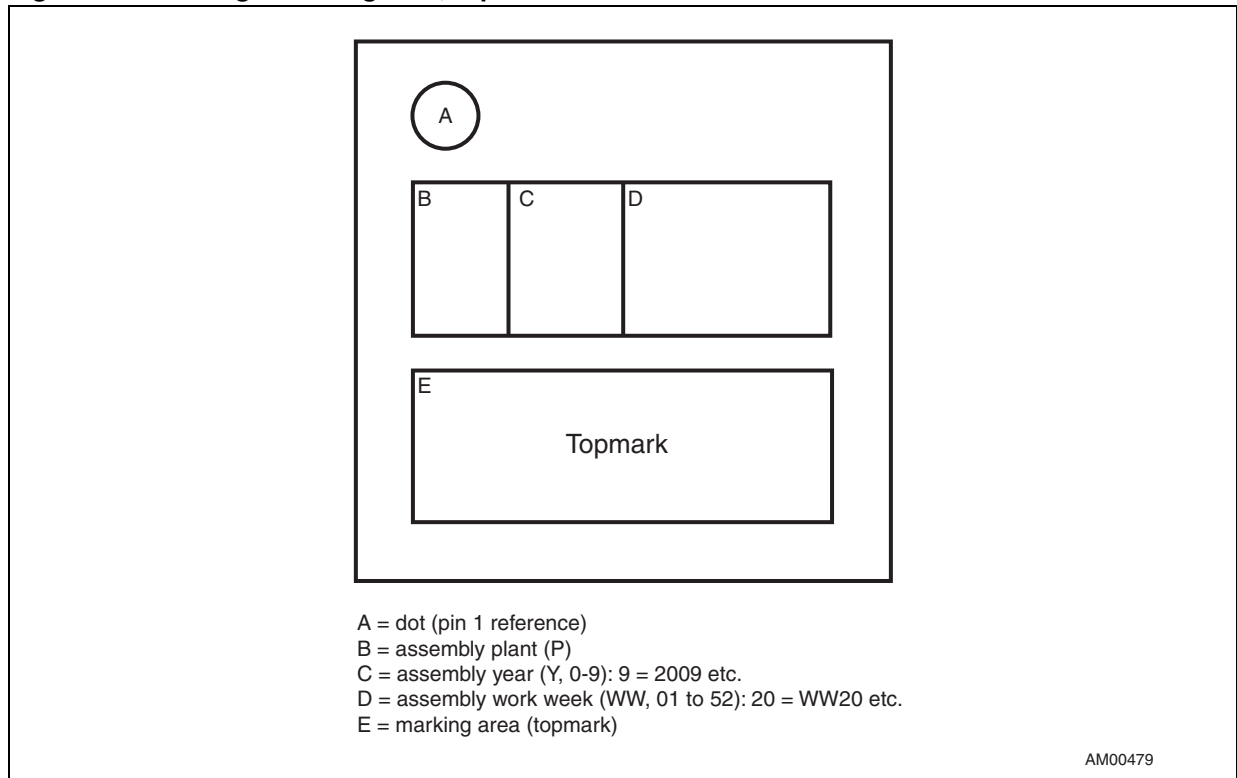
## 12 Package marking information

Table 12. Package marking

Full part number	t <sub>SR</sub> delay control	Smart Reset inputs type	V <sub>RST</sub>	RST1 output type	t <sub>REC1</sub> programming	RST2 output type	t <sub>REC2</sub> option	Topmark
STM6513VEIEDG6F	TSR	AL, NPU	V	AH, PP	C <sub>tREC</sub>	AL, OD, NPU	E	9AH
STM6513SEIEDG6F	TSR	AL, NPU	S	AH, PP	C <sub>tREC</sub>	AL, OD, NPU	E	9SH
STM6513REIEDG6F	TSR	AL, NPU	R	AH, PP	C <sub>tREC</sub>	AL, OD, NPU	E	9RH

Note: AL = active-low, AH = active-high; PP = push-pull, OD = open-drain, PU = internal pull-up resistor, NPU = no internal pull-up resistor.

Figure 19. Package marking area, top view



## 13 Revision history

**Table 13. Document revision history**

Date	Revision	Changes
22-Oct-2009	1	Initial release.
21-Jun-2010	2	Updated title, <i>Features, Applications</i> , replaced “smart reset” by “Smart Reset™” and “Smart Reset”, updated <i>Section 1, Table 1, Section 3, Table 2, Figure 3, Figure 5, Figure 6, Table 3, Table 5 to Table 8, Table 11 and Table 12.</i>

**Please Read Carefully:**

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

**UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.**

**UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.**

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2010 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

[www.st.com](http://www.st.com)

## Данный компонент на территории Российской Федерации

### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9